

NOTE:

1. MATERIAL:

- 1.1 INSULATOR: LCP+30%GF, UL94 V-0.
- 1.2 CONTACT 1~4PIN: C5191-EH.
- 1.3 CONTACT 5~9PIN: C5191-EH.
- 1.4 SHELL: SUS304 3/4H

2. PLATING:

2.1 CONTACT:

CONTACT AREA: GOLD PLATING.

SOLDER AREA: 100u" Min MATTE TIN PLATING.

UNDER PLATE: 50u" Min NICKEL PLATING.

2.2 SHELL: 50u" Min. NICKEL PLATED OVERALL

3. CHARACTERISTICS:

3.1 ELECTRICAL CHARACTERISTICS:

CONTACT RESISTANCE: 30mΩ MAXIMUM

CONTACT CURRENT RATING: 3A

DIELECTRIC WITHSTANDING VOLTAGE: 500 V R.M.S.

INSULATION RESISTANCE: 100 MEGOHMS MIN

OPERATING TEMPERATURE: -25° C ~ +85° C

3.2 MECHANICAL:

MATING FORCE: 8-25N.

UNMATING FORCE: 10-25N.

After lifespan testing: 6N Min.

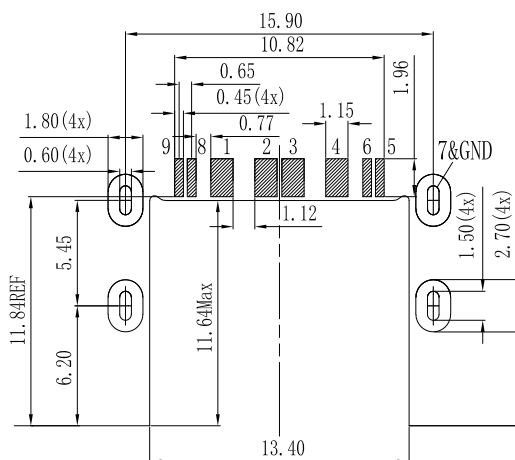
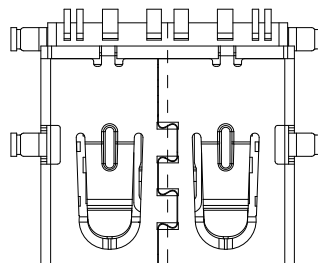
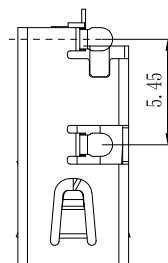
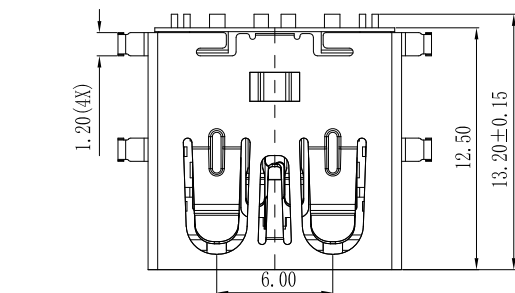
4. PART MUST COMPLY ROHS SPECIFICATION

5. WAVE SOLDER: THE CONNECTOR SHALL BE MOUNTED

ON THE PCB. THE TEMPERATURE OF THE SOLDER SHALL

BE 260±5° C AND IMMERSION DURATION 5 SECONDS.

6. ROHS. HF

TOLERANCE: ±0.05, RECOMMENDED PCB LAYOUT
(TOP VIEW)

Pin NUMBER	SIGNAL NAME
1	VBUS
2	D-
3	D+
4	GND
5	StdA_SSRX-
6	StdA_SSRX+
7	GND_DRAIN
8	StdA_SSTX-
9	StdA_SSTX+
Shell	Shield

3	SHELL	SUS304-3/4H	50u" Min. NICKEL PLATED OVERALL
2	CONTACT	C5191-EH	GOLD PLATED ON CONTACT AREA
1	HSG	LCP+30%GF	UL94V-0 BLACK
NO.	PART NAME	MATERIAL	DESCRIPTION



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TOLERANCE:

XX ±0.30
XX ±0.25
XXX ±0.15

X° ±2° X.X° ±0.5°



UNIT: mm [inch]

SCALE: 1:1

SIZE: A4

DRAWN BY :

陈一鸣

DATE :

2014-02-23

PART NAME:

USB 3.1 AF 10Gbps 沉板 H=3.5mm

CHECKED BY:

马跃

DATE :

2014-02-23

PART NO.

HYCW184-USBA09-350B

APPROVED BY:

邱敏

DATE :

2014-02-23

DRAW NO:

HYC-2604281543

SHEET NO.

1 OF 1